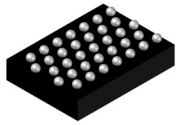


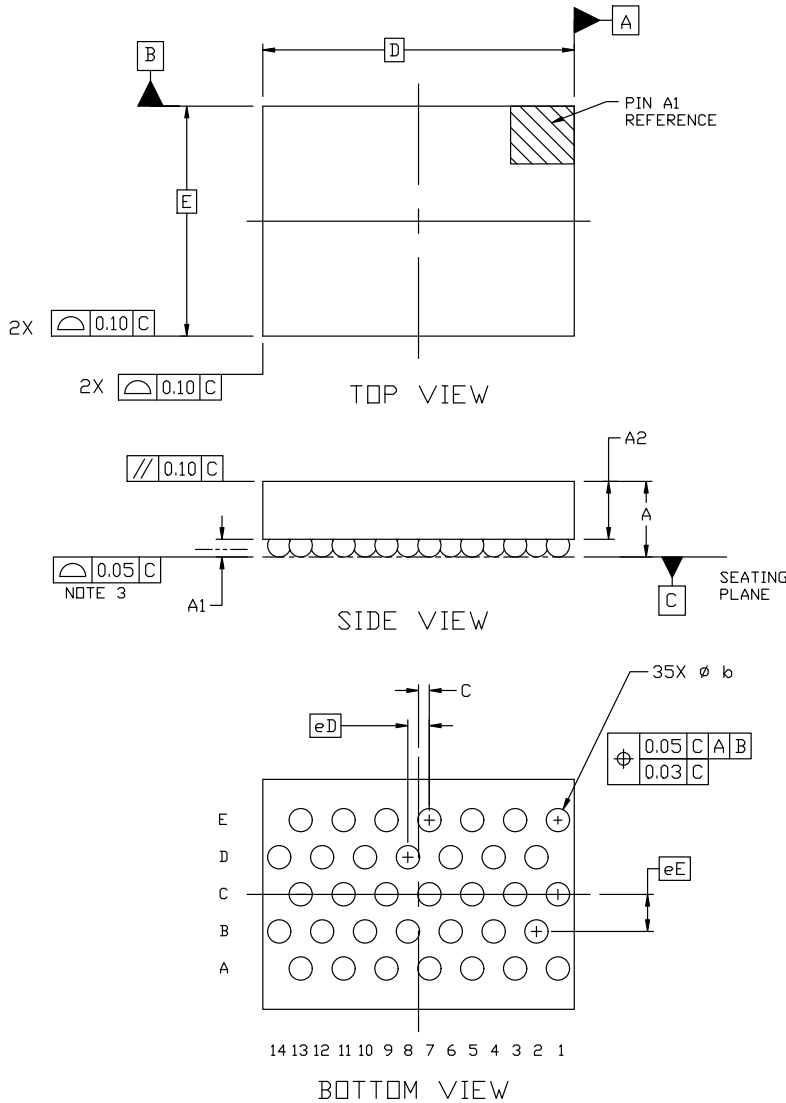
MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS



WLCSP35, 3.63x2.68
CASE 567AG
ISSUE C

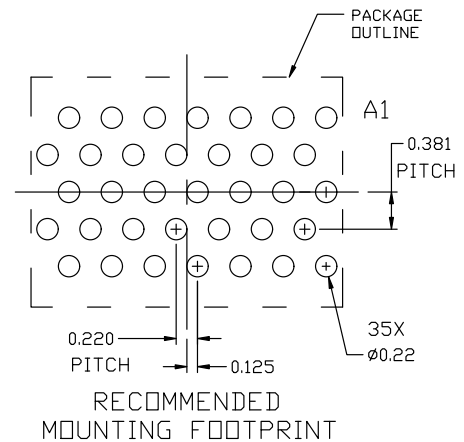
DATE 20 OCT 2022



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.832	0.882	0.932
A1	0.182	0.207	0.232
A2	0.650	0.675	0.700
b	0.244	0.269	0.294
C	0.125 BSC		
D	3.633 BSC		
E	2.680 BSC		
eD	0.250 BSC		
eE	0.433 BSC		



* For additional information on our Pb-free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP35, 3.63X2.68	PAGE 1 OF 1

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